

VISION FOR THE FUTURE

Emmanuel SABONNADIERE – IEDM December 2nd, 2018



LETI'S INNOVATION DAYS 2018: "BRAIN INSPIRED" LETI'S INNOVATION DAYS 2019: "DEEP TECH FOR EDGE AI"



June 24-28, 2019 Grenoble, France









3



LETI'S INNOVATION DAY IN TAIWAN IN 2018 - FIRST EDITION



SA TECHNOLOGY Kingyoup Optronics Winbond Formose Material Industrial Tranwo Technology Catch Technology Silicon Jazz Nanya Technology Corporation Sun-Opto Technology Brewer ScienceEVG-TWAveni Intel Semco Technologies TSMC Maojet Technology AutoChips TSMC Maojet Technology AutoChips TSMC Maojet Technology AutoChips TSMC Maojet Technology Macronix International Taiwan Instrument Daxin Materials Vise Pioneer Display Kise Pioneer Display Leaderon Materials Technology UMC Eucarla Industrial Telena Purity Energy Taihoya Corporation Silferra Kromax International TSI semiconductor AUO

| 4





COLLABORATION AGREEMENT LETI & IMEC CREATE A EUROPEAN MOMENTUM





Quantum Technologies + Neuromorphic Architectures









LETI, PIONEERING THE FUTURE OF MICROELECTRONICS WITH YOU



CEA

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SCIENCE: AN OPINION LEADER IN THE SCIENTIFIC COMMUNITY

5 domains of Expertise:



Top level academic partners



Massachusetts Institute of Technology



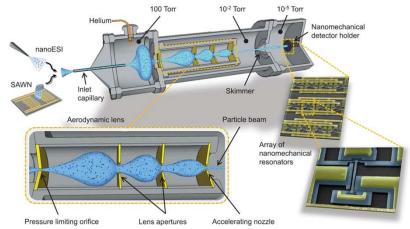
New scientific report 2018



NEW MASS-SPECTRONOMY TECHNOLOGY

FRENCH RESEARCHERS WEIGH WHOLE VIRUS CAPSIDS AND EXTEND REACH OF MASS SPECTROMETRY WITH NANOMECHANICAL RESONATORS

A team of French researchers at Leti has demonstrated a new mass-spectrometry technology based on nanomechanical resonators that measures the mass of particles previously beyond the reach of current commercial technology, and which they used to measure the mass of a whole bacteriophage virus capsid.



Fore more information : http://science.sciencemag. org/content/362/6417/918



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Leti HEALTHCARE AT LETI, INNOVATING FOR OVER 35 YEARS...

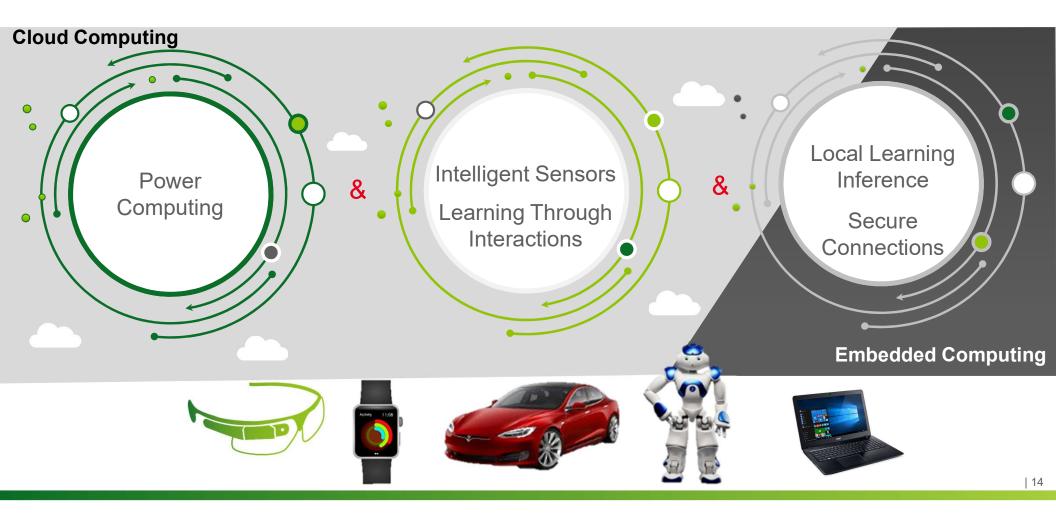


| 11



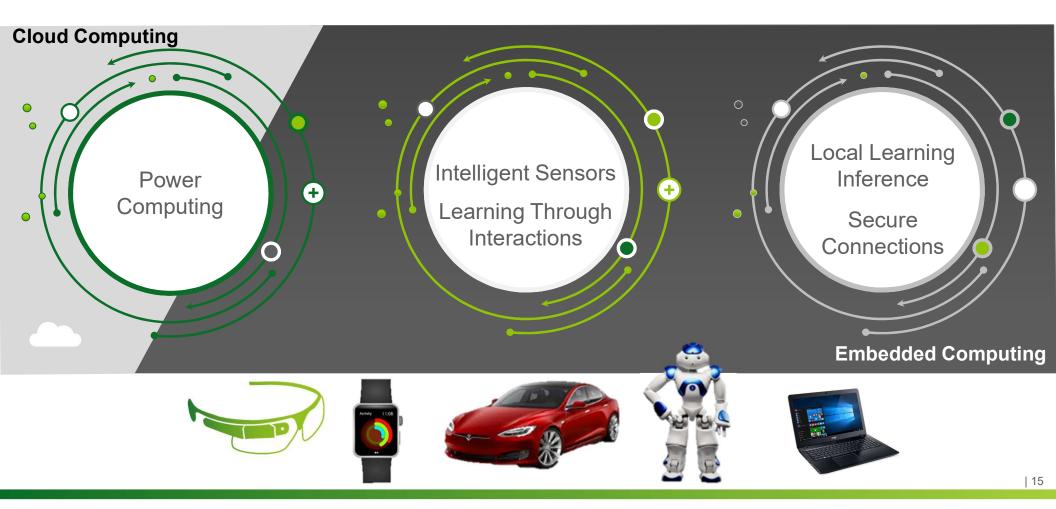


TOWARDS A PERVASIVE INTELLIGENCE TODAY: STRONG LINK WITH THE CLOUD

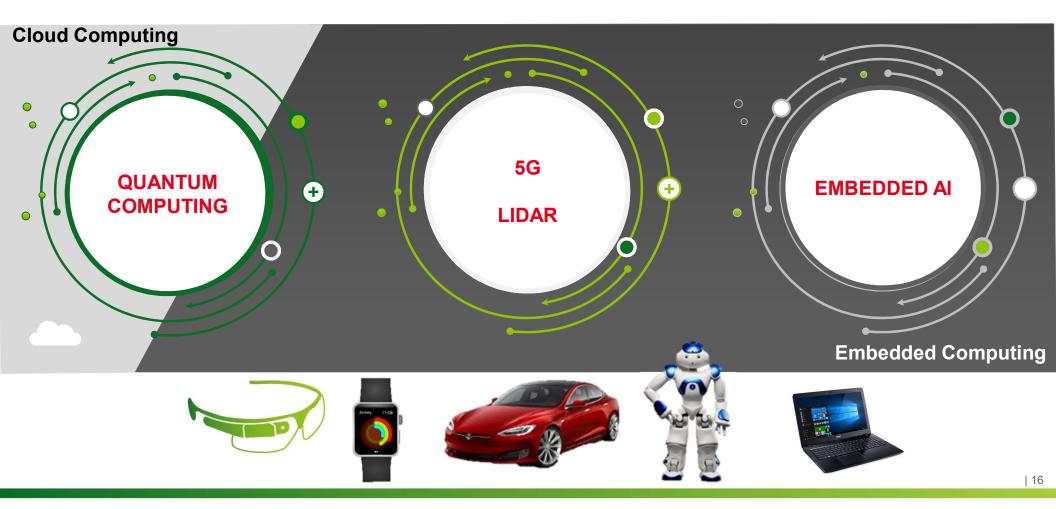




TOWARDS A PERVASIVE INTELLIGENCE TOMORROW: MORE & MORE EMBEDDED INTELLIGENCE









CURVING TECHNOLOGY FOR OLED MICRODISPLAYS

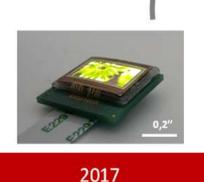
Major Results

- OLED microdisplay Scale-up, diagonal = 1", R=45 mm
- Well-performing displays

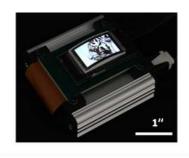
Expected Results

Combine an optical system with a curved microdisplays, and integrate this technology into compact VR head-mounted displays





Maryland display, 0,38", R=45 mm Monochrome jaune



2018

LOMID display, 1", R=45 mm Monochrome blanc



Large cost-effective OLED microdisplays

leti

LETI IS PRESENTING 11 KEY PAPERS AT IEDM 2018

Monday, Dec. 3

Breakthroughs in 3D Sequential Technology Session 7.2 Time: 2:00 pm

Towards Scalable Silicon Quantum Computing (invited) Session 6.2 Time: 2:00 pm

Hybrid Bonding for 3D Stacked Image Sensors: Impact of Pitch Shrinkage on Interconnect Robustness Session 7.3 Time: 2:25 pm

Tuesday, Dec. 4

Very Large Scale Integration Optomechanics: A Cure for Loneliness of NEMS Resonators? Session 12.4 Time: 9:00 am

Characterization Methodology and Physical Compact Modeling of in-Wafer Global and Local Variability Session 17.1 Time: 9:05 am

Development of X-ray Photoelectron Spectroscopy Under Bias and its Application to Determine Bandenergies and Dipoles in the HKMG Stack Session 17.6: Time: 11:35 am

In-depth Characterization of Resistive Memory-based Ternary Content Addressable Memories Session 20.3: Time: 3:10 pm

Tunability of Parasitic Channel in Gate-All-Around Stacked Nanosheets Session 21.3: Time: 3:10 pm

Wednesday, Dec. 5

Optimized Reading Window for Crossbar Arrays Thanks to Ge-Se-Sb-N-based OTS Selectors

Session 37.4: Time: 2:50 pm

Truly Innovative 28nm FDSOI Technology for Automotive Micro-Controller Applications Embedding 16MB Phase Change Memory Session 18.4: Time: 4:00 pm

In-Memory and Error-Immune Differential RRAM Implementation of Binarized Deep Neural Networks Session 20.6: Time: 4:50 pm

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SPICE COMPACT MODELS FOR CIRCUIT DESIGN AND TECHNOLOGY CO-OPTIMIZATION

Project combines CEA-Leti's compact modeling expertise and Silvaco's extensive experience in SPICE compact model integration and extraction

19

Iliya PESIC Executive Chairman Of the Board





Technologies for New Computing Paradigms

Dr. Carlo Reita Director Technical Marketing Strategy, Nanoelectronics, Leti



Emerging Non-Volatile Memories for Computing

Dr. Marie Claire Cyrille Director Technical Marketing Strategy, Advanced Computing, Leti



Dr. Denis Dutoit Director Technical Marketing Strategy, Advanced Computing, Leti

> Enabling Heterogeneous High Performance Processors



Quantum Computing on Silicon
Dr. Maud Vinet
Advanced CMOS Laboratory Manager, Leti



Future opportunities in high performance and low power computing with emerging technologies and novel architectures

Dr. John Paul Strachan Rebooting Computing Research Group Manager, HPE